

# NX3026RH GaN TRANSISTOR

Document Number: NX3026RH  
Preliminary Datasheet V1.1

## Gallium Nitride 28V 260W, RF Power Transistor

### Description

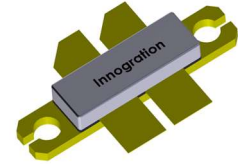
The NX3026RH is a 260W 28V, GaN HEMT, designed for multiple applications with frequencies up to 2.7GHz.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

- Typical performance (on Innogration narrow band fixture with device soldered)

$V_{DD}=28V$   $I_{DQ}=130mA$ , CW.

**NX3026RH**



NX3026RH		VGS=-2.48V		VDS=28V		IDQ=130mA		CW
Freq (MHz)	Psat (dBm)	Psat (W)	IDS (A)	Pin (dBm)	Gain (dB)	Eff(%)	2nd (dBc)	3rd (dBc)
200	52.31	170.2	6.93	32.55	19.76	87.72	-22.0	-14.5
300	52.15	164.1	7.78	32.94	19.21	75.31	-33.60	-15.70
400	52.42	174.6	9.83	32.70	19.72	63.43	-32.80	-15.60
500	52.67	184.9	12.45	33.46	19.21	53.05	-39.10	-25.00
600	53.01	200.0	10.78	34.41	18.60	66.26	-34.80	-27.20
700	53.07	202.8	9.54	35.10	17.97	75.91	-53.80	-31.10
800	52.59	181.6	9.45	36.32	16.27	68.61	-40.60	-42.70
900	52.56	180.3	9.55	36.86	15.70	67.43	-32.30	-34.80
1000	52.67	184.9	10.54	36.78	15.89	62.66	-33.70	-27.60

### Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

### Important Note: Proper Biasing Sequence for GaN HEMT Transistors

#### Turning the device ON

1. Set VGS to the pinch-off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage (28V)
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

#### Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

**Table 1. Maximum Ratings (Not simultaneous, TC = 25°C unless otherwise noted)**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DS}$	150	Vdc
Gate--Source Voltage	$V_{GS}$	-10,+2	Vdc
Operating Voltage	$V_{DD}$	36	Vdc
Maximum Forward Gate Current	$I_{gmax}$	60	mA
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C

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Operating Junction Temperature(See note 1)	$T_J$	+225	°C
Total Device Power Dissipation (Derated above 25°C, see note 2)	$P_{diss}$	240	W

1. Continuous operation at maximum junction temperature will affect MTTF
2. Bias Conditions should also satisfy the following expression:  $P_{diss} < (T_J - T_C) / R_{JC}$  and  $T_C = T_{case}$

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_C = 85^\circ\text{C}$ , $T_J = 200^\circ\text{C}$ , DC Power Dissipation(See note 1)	$R_{\theta JC-DC}$	0.8	C/W

$R_{\theta JC-DC}$  is tested at only DC condition, it is related to the highest thermal resistor value among all test conditions. It might be differently lower in different RF operation conditions like CW signal ,pulsed RF signal etc.

**Table 3. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

## DC Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8\text{V}$ ; $I_{DS} = 60\text{mA}$	$V_{DSS}$	150			V
Gate Threshold Voltage	$V_{DS} = 28\text{V}$ , $I_D = 60\text{mA}$	$V_{GS(th)}$		-2.7		V
Gate Quiescent Voltage	$V_{DS} = 28\text{V}$ , $I_{DS} = 2000\text{mA}$ , Measured in Functional Test	$V_{GS(Q)}$		-2.45		V

**Functional Tests (In Innogration narrow band Test Fixture, 50 ohm system) :**  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ} = 2000\text{ mA}$ ,  $f = 1300\text{ MHz}$ , CW

Characteristic	Symbol	Min	Typ	Max	Unit
Power Gain @ $P_{sat}$	$G_p$		16		dB
Drain Efficiency @ $P_{sat}$	$Eff$		65		%
Saturated Power	$P_{sat}$	240	260		W
Input Return Loss	IRL		-7		dB
Mismatch stress at all phases (Device no damage)	VSWR		10:1		$\Psi$

## Reference Circuit of Test Fixture Assembly Diagram

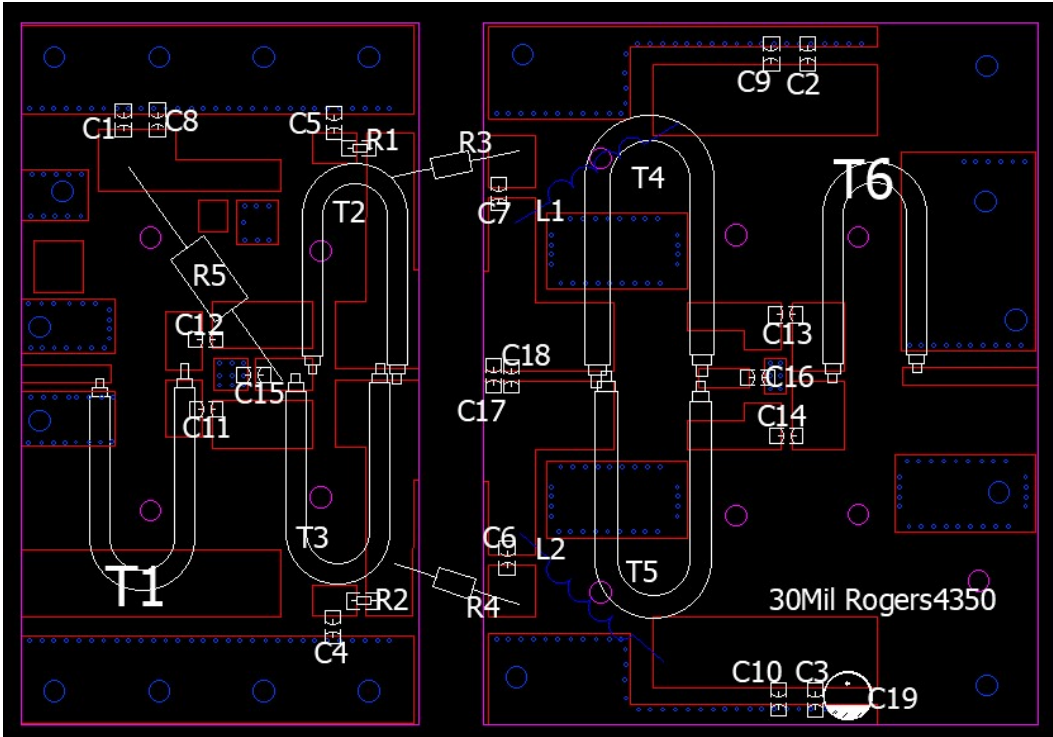


Figure 1. Test Circuit Component Layout (200-1000MHz)

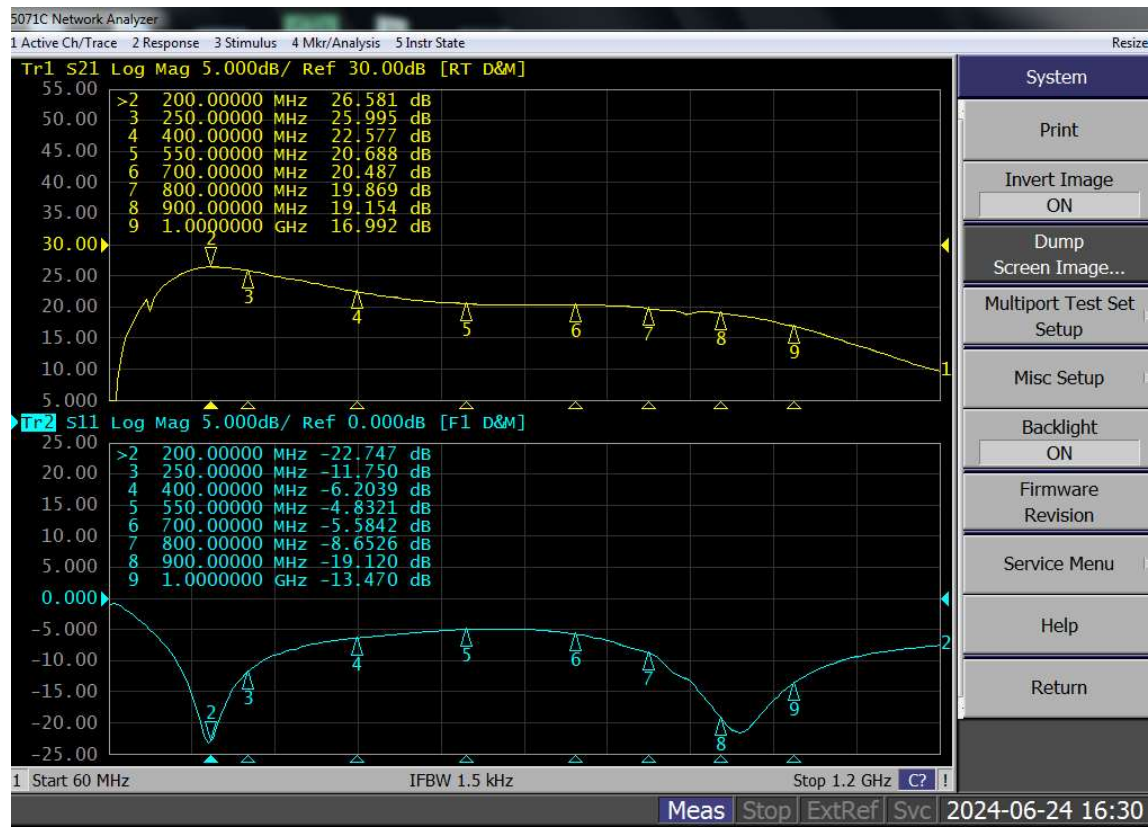
Table 4. Test Circuit Component Designations and Values

Component	Description	Suggestion
C1~C7	10uF/100V-1210	Ceramic multilayer capacitor
C8~C10,C15,C16	820pF	BEIJING YUANLU HONGYUAN ELECTRONIC TECHNOLOGY CO., LTD.MQ301111
C11~C14	270pF	BEIJING YUANLU HONGYUAN ELECTRONIC TECHNOLOGY CO., LTD.MQ301111
C17	9.1pf	BEIJING YUANLU HONGYUAN ELECTRONIC TECHNOLOGY CO., LTD.MQ301111
C18	3pF	BEIJING YUANLU HONGYUAN ELECTRONIC TECHNOLOGY CO., LTD.MQ301111
C19	470uF/63V	Electrolytic Capacitor
R1,R2	10 $\Omega$ -1206	Chip Resistor
R3~R5	300 $\Omega$ -3W	Color ring resistance
L1,L2	1.5mm wire, 3mm innerdiameter, 2turns	DIY
T1	50 ohm, 70mm	RFSFBU-086-50
T2~T5	16.7 ohm, 50mm	SFF-16.7-1.5
T6	50 ohm, 80mm	RFSFBU-086-50
PCB	30Mil Rogers4350	

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Figure 2. Network Analyzer result S11 and S21



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## Package Outline

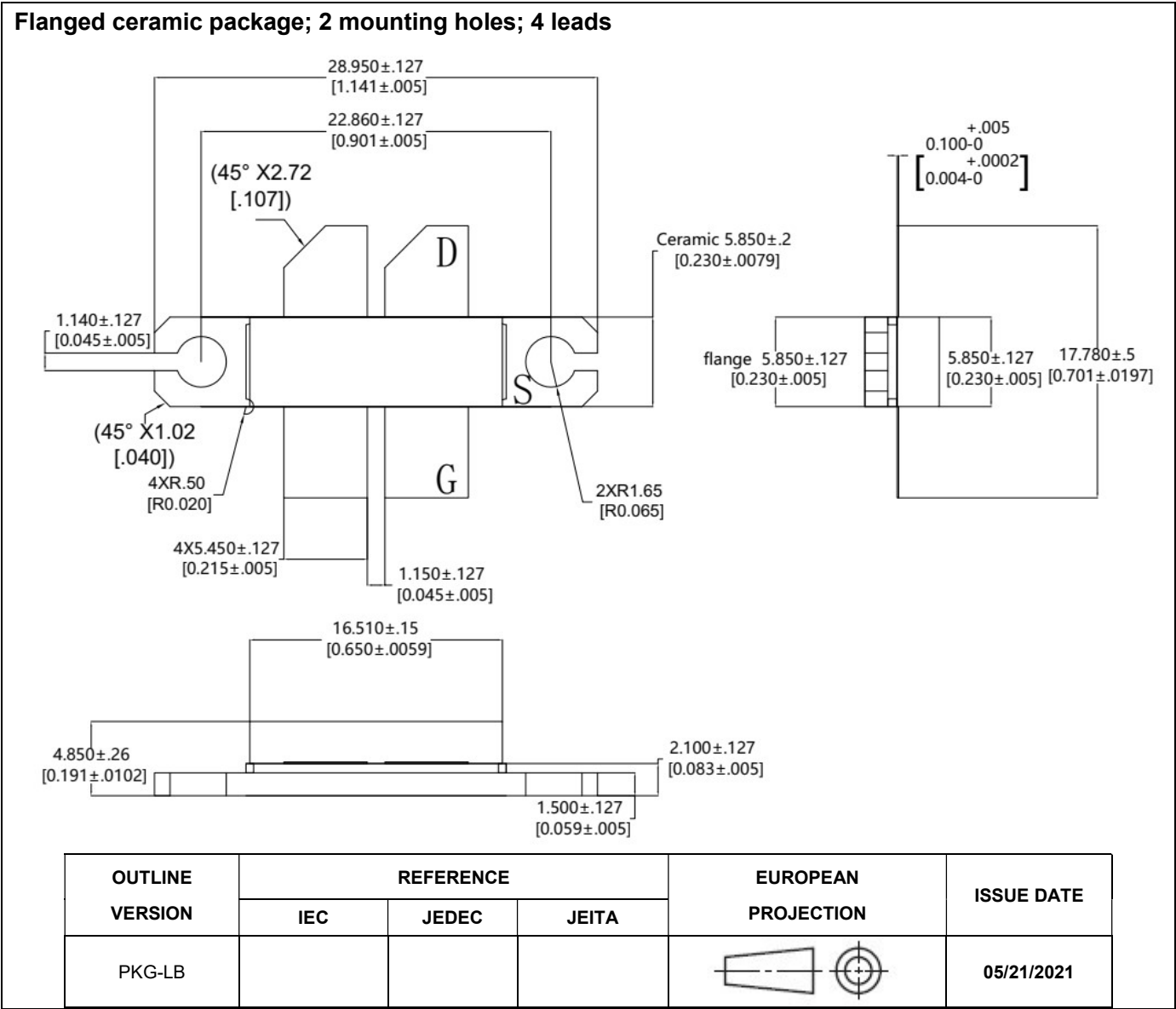


Figure 1. Package Outline PKG-LB(LBB)

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## Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2021/11/22	V1.0	Preliminary datasheet creation
2024/6/24	V1.1	Add application data

Application data based on TC-24-40

## Notice

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